

## LPXSMB31-S50C

OSFP, 400G DR4, MPO-12, 1310nm SMF, 500m

### Features

- Data rate up to 425Gbps (4xPAM4 53.125 GBd)
- Silicon photonics integrated solution with optical DSP CDR inside
- 400GAUI-4 High speed I/O electrical interface
- OSFP Hot-pluggable form factor
- Maximum link length of 500m on SMF with FEC
- Single 3.3V power supply
- Power dissipation : < 12W
- Single MPO-12(APC) connector
- Operating case temp: 0°C to +70 °C
- RoHS 6 Compliant

### Applications

- 400GBASE-DR4
- 200GBASE-DR2
- 100GBASE-DR1

### Order Information

Part NO.	Bit Rate	Laser	Distance *1	Fiber Media	DDMI	Connector	Temp *2
LPXSMB31-S50C	425.Gbps	1310nm	500m	SMF	YES	1 × MPO-12 (APC)	0 ~ +70℃

Note:

1. on SMF , with FEC;
2. Case Temperature.

## I. Absolute Maximum Ratings

Parameter	Symbol	Min.	Typ.	Max.	Unit	Notes
Supply Voltage	VCC	-0.5	-	+3.6	V	
Storage Temperature	T <sub>s</sub>	-40	-	+85	°C	
Operating Humidity	RH	5	-	85	%	No condensation
Optical Receiver Damage Threshold	Rin <sub>dam</sub>	5			dBm	each lane

## II. Recommended Operating Conditions

Parameter	Symbol	Min.	Typ.	Max.	Unit	Notes
Operating Case Temperature	T <sub>C</sub>	0	-	+70	°C	
Power Supply Voltage	Vcc	3.135	3.3	3.465	V	
Power Dissipation	Pd	-	-	12	W	
Link distance	d	2		500	meters	SMF, with FEC

## III. Optical Characteristics

Parameter	Symbol	Min	Typ	Max	Unit	Notes
<b>Transmitter</b>						
Signaling Rate per Lane		53.125 ± 100 ppm			GBd	
Modulation Format		PAM4				
Lane Center Wavelengths (range)	λ <sub>C</sub>	1304.5		1317.5	nm	
Side-mode Suppression ratio (SMSR)	SMSR	30			dB	
Average Launch Power, each lane		-2.9		4	dBm	
Outer Optical Modulation Amplitude, (OMA outer), each Lane	OMA	-0.8		4.2	dB	
Launch power in OMA outer minus TDECQ		-2.2			dB	
Transmitter and dispersion eyeclosure for PAM4 (TDECQ), each lane				3.4	dBm	
Optical Extinction Ratio	ER	3.5			dB	
Optical Return Loss Tolerance				21.4	dB	
<b>Receiver</b>						
Signaling Rate per Lane		53.125 ± 100 ppm			GBd	
Modulation Format		PAM4				

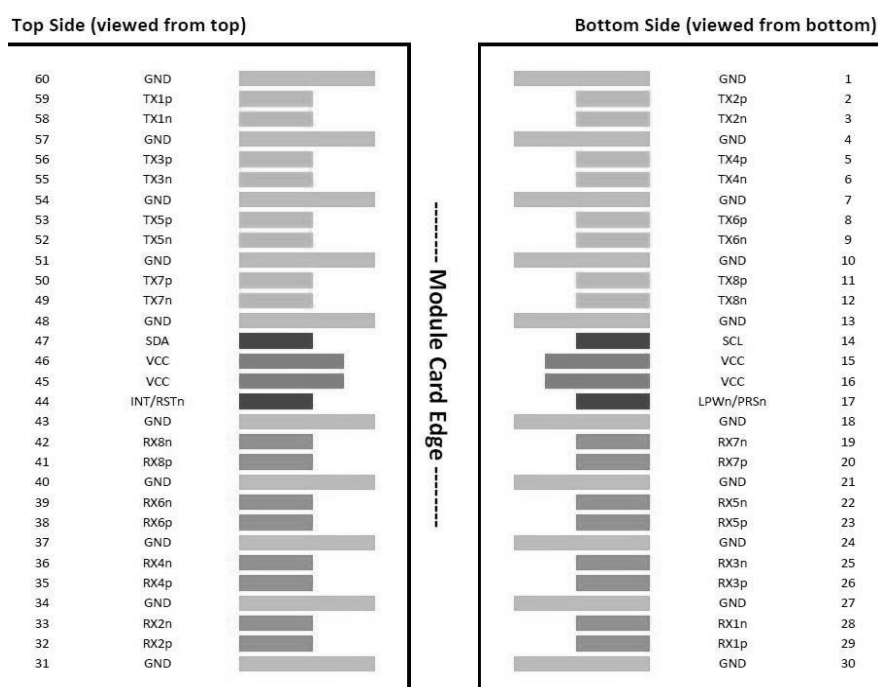
Lane Center Wavelengths (Range)	$\lambda_C$	1304.5		1317.5	nm	
Average Receive Power, each Lane		-5.9		4	dBm	
Receive Power (OMA outer), each Lane				4.2	dBm	
Receiver Reflectance				-26	dB	
Stressed Receiver Sensitivity (OMA outer), each Lane				-1.9	dBm	
Receiver Sensitivity (OMA outer), each Lane				-4.4	dBm	
Los Assert	LOS <sub>Assert</sub>	-14	-	-11.5	dBm	
Los De-assert	LOS <sub>De-</sub>	-11	-	-8	dBm	
LOS Hysteresis	LOS <sub>Hys</sub>	0.5	-	4	dB	

#### IV. Electrical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Notes
Supply Voltage	V <sub>CC</sub>	3.135		3.465	V	
Power Dissipation	P <sub>d</sub>			12	W	
Transmitter(per Lane)						
Data Rate, each lane	DR	53.125			GBd	
Signaling rate per lane (range)	-	-100ppm	53.125	+100ppm	GBd	PAM4
Modulation Format	-	PAM4			-	
Differential Input Peak-peak Voltage Tolerance	V <sub>in-diff</sub>	750	-	-	mVpp	
Differential Input Termination Mismatch	-	-	-	10	%	
Single-ended Voltage Tolerance	-	-0.4	-	3.3	V	
DC Common-mode Voltage Tolerance	-	-0.35	-	2.85	V	
Receiver (per Lane)						
Data Rate, each lane	DR	53.125			GBd	
Data Rate Variation	-	-100	-	+100	ppm	
Modulation Format	-	PAM4			-	
Differential Output Peak-to-peak Voltage (Short mode)	V <sub>out-diff,short</sub>	-	-	600	mVpp	
Differential Output Peak-to-peak Voltage (Long mode)	V <sub>out-diff,Long</sub>	-	-	845	mVpp	
Transition Time (20% to 80%)	Tr/tf	8.5	-	-	ps	

Eye Height	EH	-	-	15	mV	
Vertical Eye Closure	VEC	-	-	12	dB	
Differential Output Termination Mismatch	-	-	-	10	%	
DC Common-mode Voltage Tolerance	-	-0.35	-	2.85	V	

## V. Pin Diagram



## Pin Function Definitions

Pin	Symbol	Name/Description	Notes
1	GND	Ground	1
2	TX2p	Transmitter Data Non-Inverted	
3	TX2n	Transmitter Data Inverted	
4	GND	Ground	1
5	TX4p	Transmitter Data Non-Inverted	
6	TX4n	Transmitter Data Inverted	
7	GND	Ground	1
8	NC	NC,unsued	2
9	NC	NC,unsued	2
10	GND	Ground	1
11	NC	NC,unsued	2
12	NC	NC,unsued	2
13	GND	Ground	1
14	SCL	2-wire Serial interface clock	3
15	VCC	+3.3V Power	

16	VCC	+3.3V Power	
17	LPWn/PRSn	Low-Power Mode/Module Present	
18	GND	Ground	1
19	NC	NC,unsued	2
20	NC	NC,unsued	2
21	GND	Ground	1
22	NC	NC,unsued	2
23	NC	NC,unsued	2
24	GND	Ground	1
25	RX3n	Receiver Data Inverted	
26	RX3p	Receiver Data Non-Inverted	
27	GND	Ground	1
28	RX1n	Receiver Data Inverted	
29	RX1p	Receiver Data Non-Inverted	
30	GND	Ground	1
31	GND	Ground	1
32	RX2p	Receiver Data Non-Inverted	
33	RX2n	Receiver Data Inverted	
34	GND	Ground	1
35	RX4p	Receiver Data Non-Inverted	
36	RX4n	Receiver Data Inverted	
37	GND	Ground	1
38	NC	NC,unsued	2
39	NC	NC,unsued	2
40	GND	Ground	1
41	NC	NC,unsued	2
42	NC	NC,unsued	2
43	GND	Ground	1
44	INT/RSTn	Module Interrupt / Module Reset	
45	VCC	+3.3V Power	
46	VCC	+3.3V Power	
47	SDA	2-wire Serial interface data	3
48	GND	Ground	1
49	NC	NC,unsued	2
50	NC	NC,unsued	2
51	GND	Ground	1
52	NC	NC,unsued	2
53	NC	NC,unsued	2
54	GND	Ground	1
55	TX3n	Transmitter Data Inverted	
56	TX3p	Transmitter Data Non-Inverted	
57	GND	Ground	1
58	TX1n	Transmitter Data Inverted	
59	TX1p	Transmitter Data Non-Inverted	
60	GND	Ground	1

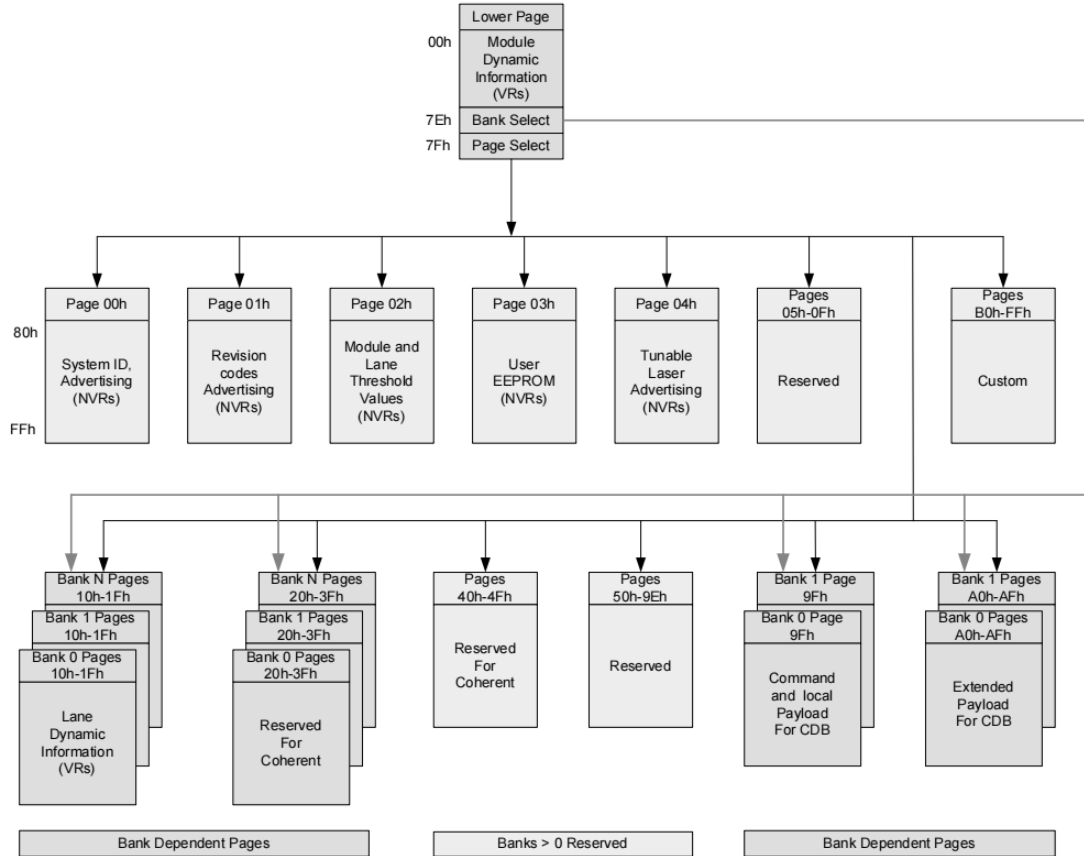
Note 1. Circuit ground is internally isolated from chassis ground.

Note 2. 400G DR4 unused PINs, NC.

Note 3. Open-Drain with pull up resistor on Host.

## VI. Memory Map

Compatible with CMIS rev4.0 and upper

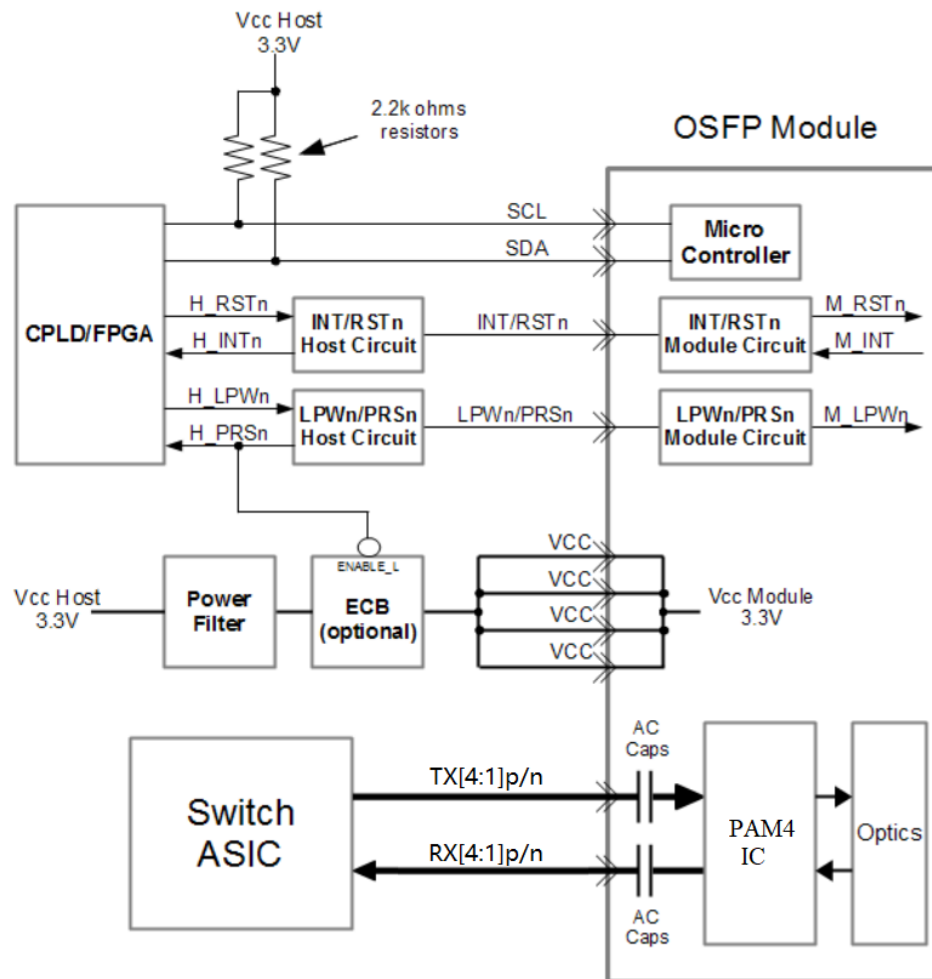


## VII. Digital Diagnostic Monitor Accuracy

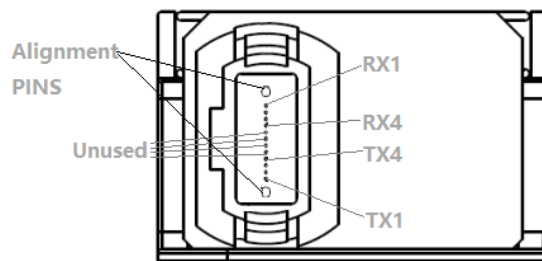
Parameter	Symbol	Unit	Min	Max	Notes
Temperature monitor absolute error	DMI_Temp	degC	-3	3	Over operating temperature range
Supply voltage monitor absolute error	DMI_VCC	V	-0.1	0.1	Over full operating range
Channel Bias current monitor	DMI_Ibias_Ch	mA	-10%	10%	
Channel TX power monitor absolute error	DMI_TX_Ch	dB	-3	3	1
Channel RX power monitor absolute error	DMI_RX_Ch	dB	-3	3	1

Note1: Due to measurement accuracy of different multi-mode fibers, there could be an additional +/- 1 dB fluctuation, or a +/- 3 dB total accuracy

## VIII. Recommended Interface



## I. Optical interface arrangement



The optical port is a male MPO connector receptacle

## IX. Mechanical Specifications

(Unit: mm)

